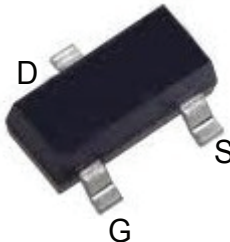
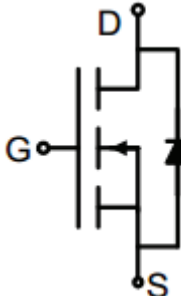




Chimicron

CM2302

N-Channel Enhancement Mode Power MOSFET

20VDS/ ±10VGS/2.9A(ID)	Part No	CM2302	
Description The NCE2302 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application. Application ●Battery protection ●Load switch ●Power management	Product Summary VDS= 20V, ID= 2.9A RDS(ON)< 59mΩ@ VGS=2.5V RDS(ON)< 45mΩ@ VGS=4.5V 		
 SOT-23 Package			
Absolute Maximum Ratings (TA=25°C unless otherwise noted)			
Parameter	Symbol	Maximum	Units
Drain-Source Voltage	VDS	20	V
Gate-Source Voltage	VGS	±10	V
Continuous Current Drain	ID	2.9	A
Pulsed Drain Current	IDM	10	A
Power Description	Pd	1	W
Operating Junction and Storage Temperature Range	Tj, TSTG	-55°C to 150°	°C
Thermal Resistance Junction to Ambient (PCB mounted) ^b	RθJA	125	°C/w

TAIWAN CHIMICRON SEMICONDUCTOR CO., LTD



Electrical Characteristics (TA=25℃unless otherwise noted)						
Parameter	symbol	Test Conditions	Min	Type	Max	Unit s
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	VGS = 0V, ID=250μA	20	22	-	V
Zero Gate Voltage Drain Current	IDSS	VDS=20V,VGS=0V	-	-	1	μA
Gate-Body Leakage Current	IGSS	VGS=±10V,VDS=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	VDS=VGS, ID=250uA	0.5	0.85	1.2	V
Drain-Source On-State Resistance	RDS(ON)	VGS=2.5V, ID=2.5A	-	37	59	mΩ
		VGS=4.5V, ID=2.9A		30	45	
Forward Trans conductance	gFS	VDS=5V,ID=2.9A	-	8	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	Ciss	VDS=10V VGS=0V, f=1.0MHz	-	300	-	PF
Output Capacitance	Coss		-	120	-	PF
Reverse Transfer Capacitance	Crss		-	80	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	td(on)	VDD=10V,ID=2.9A VGS=4.5V,RGEN=6 Ω	-	10	15	nS
Turn-on Rise Time	tr		-	50	85	nS
Turn-Off Delay Time	td(off)		-	17	45	nS
Turn-Off Fall Time	td(off)		-	10	20	nS
Total Gate Charge	Qg	VDS=10V,ID=2.9A, VGS=4.5V		4.0	10	nC
Gate-Source Charge	Qgs			0.65	-	nC
Gate-Drain Charge	Qgd		-	1.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Current (Note 2)	IS		-	-	2.9	A
Diode Forward Voltage (Note 3)	VSD	VGS=0V,IS=2.9A	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

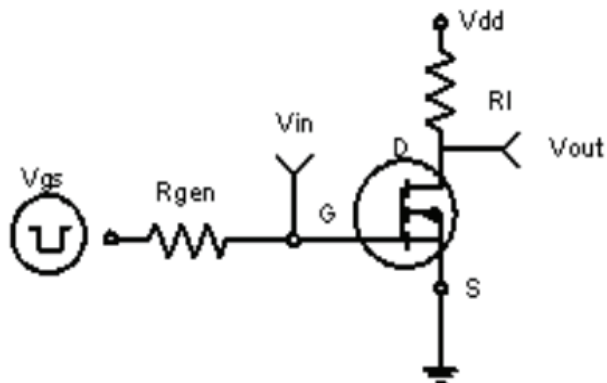


Figure 1: Switching Test Circuit

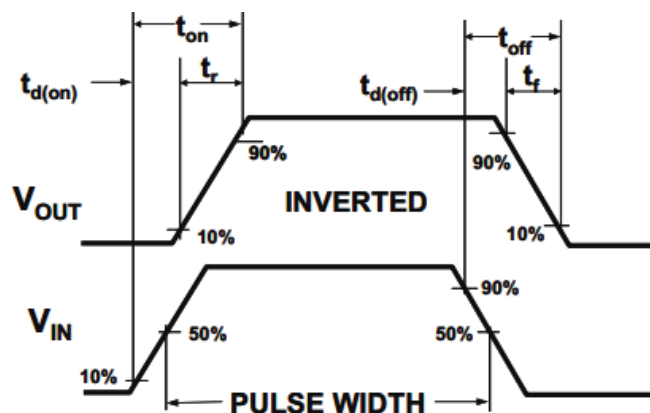
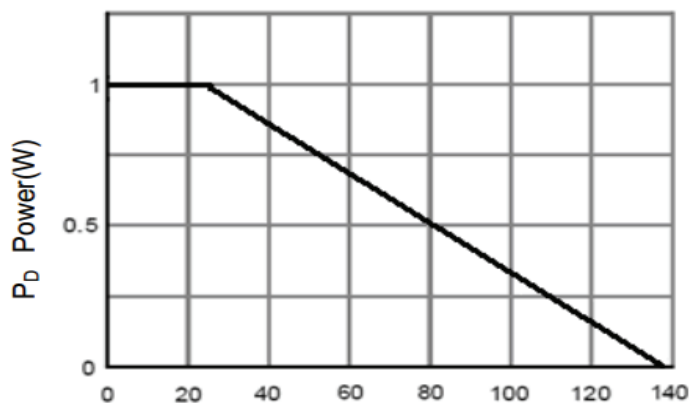
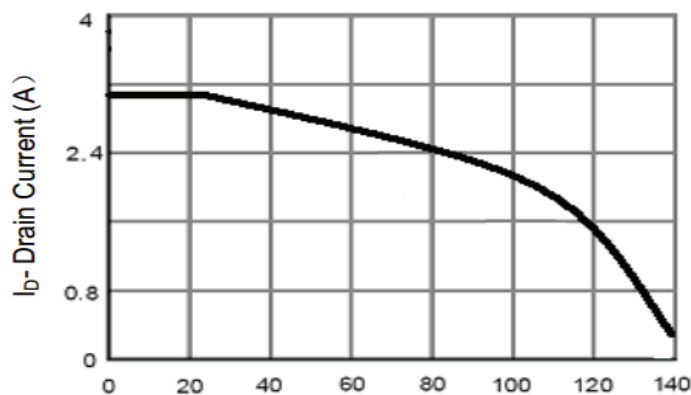


Figure 2: Switching Waveforms



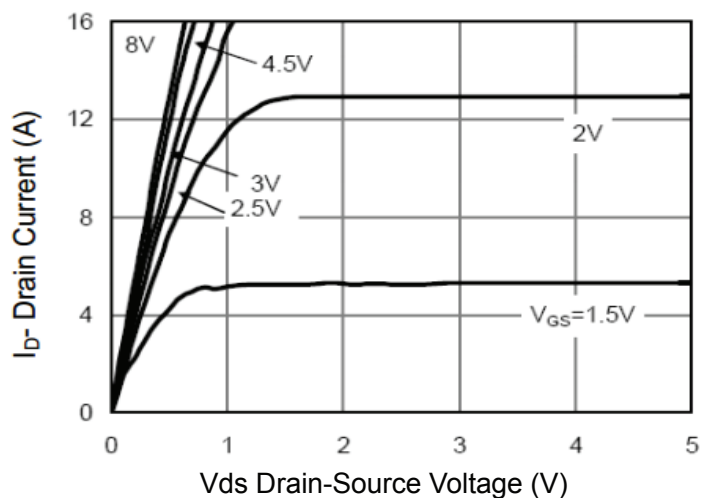
TJ-Junction Temperature(°C)

Figure 3 Power Dissipation



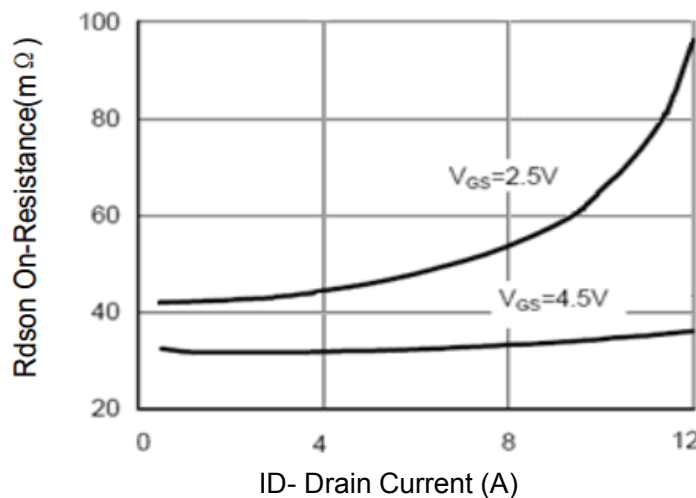
TJ-Junction Temperature(°C)

Figure 4 Drain Current



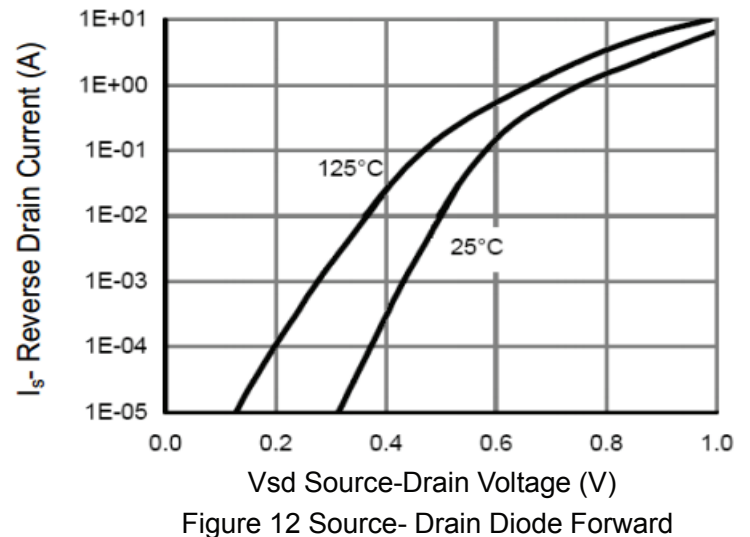
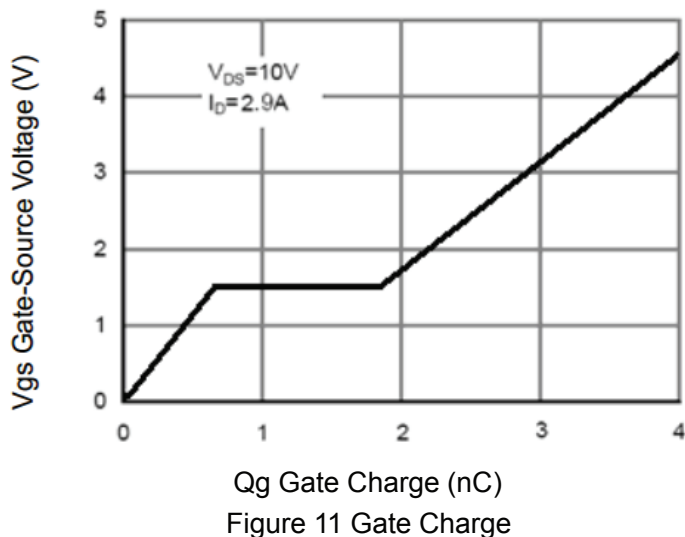
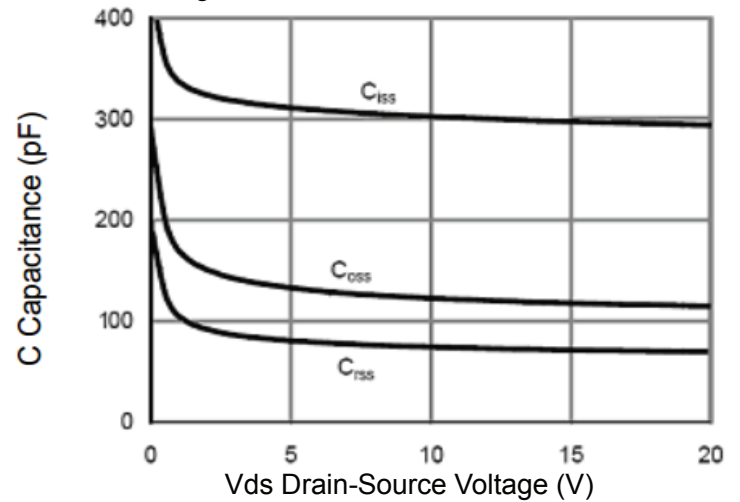
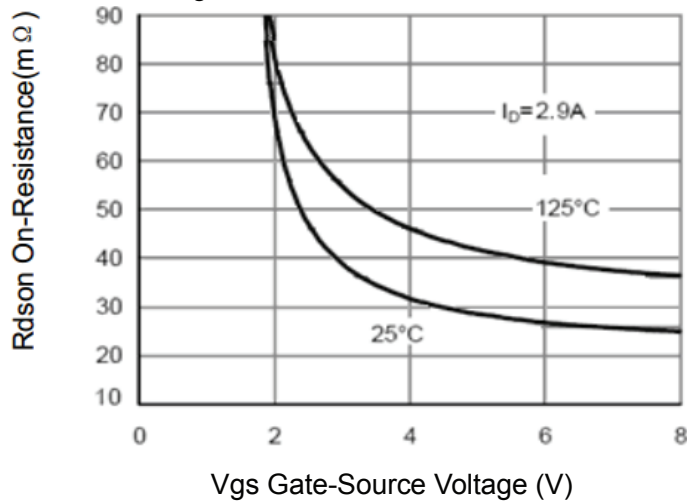
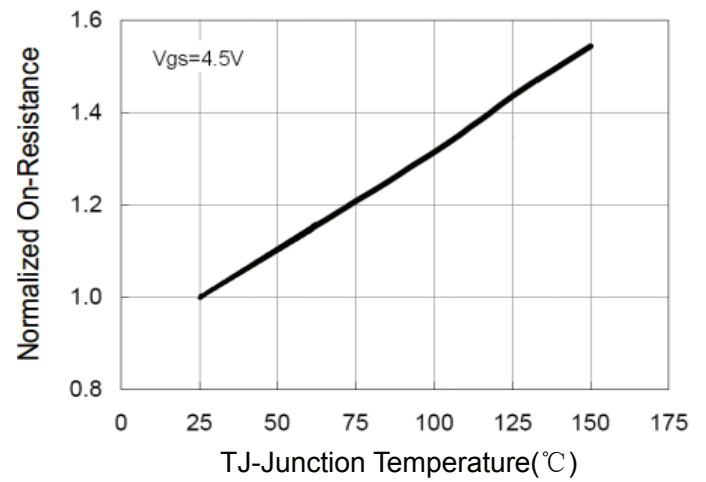
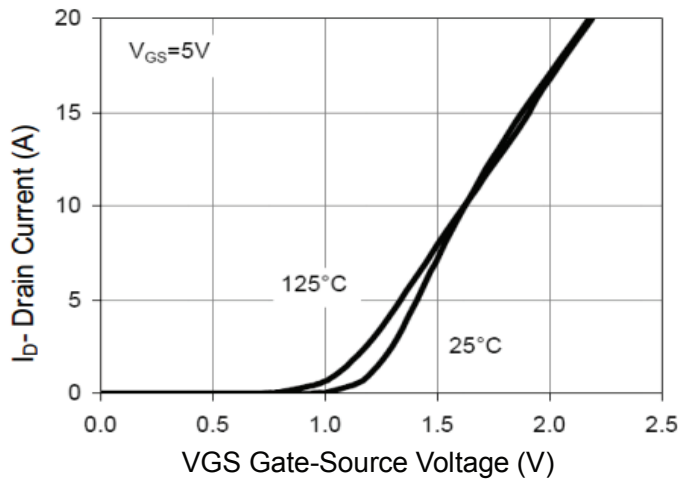
Vds Drain-Source Voltage (V)

Figure 5 Output CHARACTERISTICS



ID- Drain Current (A)

Figure 6 Drain-Source On-Resistance



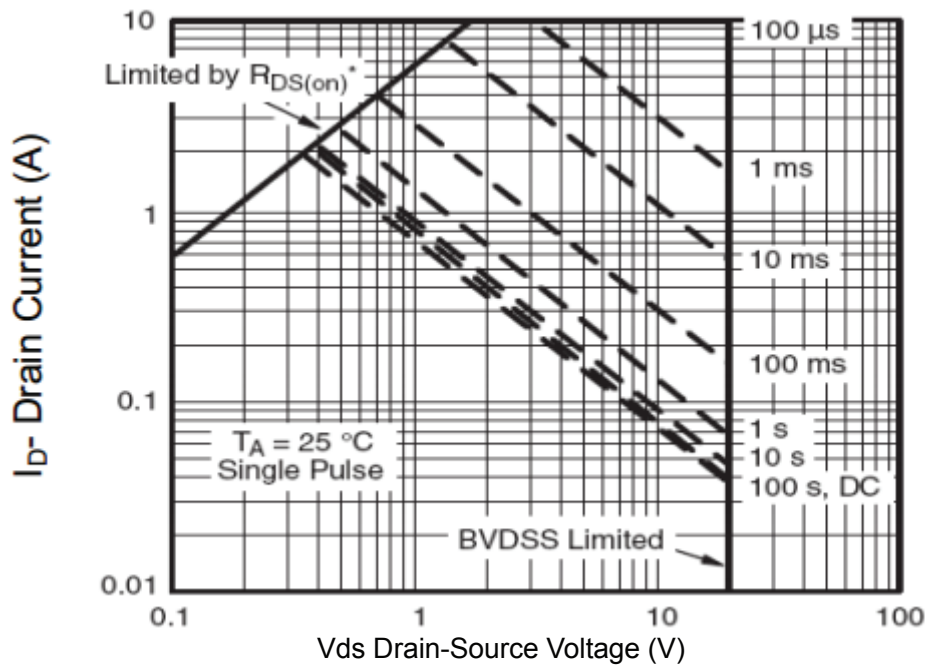


Figure 13 Safe Operation Area

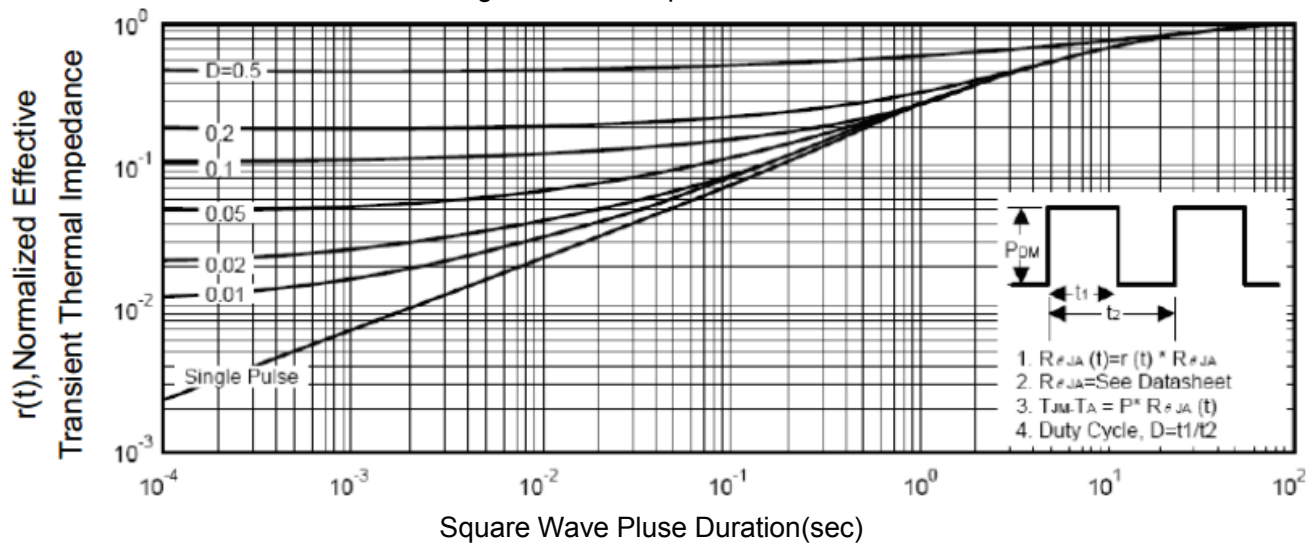


Figure 14 Normalized Maximum Transient Thermal Impedance